

PCN# 20180918001
Qualify 0.8mil Cu wire diameter for select devices
Change Notification / Sample Request

Date: September 20, 2018

To: Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20180918001
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LMV358AIDR	null
TLV9002IDR	null
TSV912AIDR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20180918001			PCN Date:	Sept 20, 2018
Title:	Qualify 0.8mil Cu wire diameter for select devices				
Customer Contact:	PCN Manager	Dept:	Quality Services		
Proposed 1st Ship Date:	Dec 20, 2018	Estimated Sample Availability:	Date Provided at Sample request		
Change Type:					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials
				<input type="checkbox"/>	Wafer Fab Process
PCN Details					
Description of Change:					
Texas Instruments Incorporated is announcing the qualification of 0.8mil Cu wire diameter for select devices listed in the "Product Affected" Section.					
Wire Diameter:					
	Current	Proposed			
Wire Diameter	1.0mil Cu wire	0.8mil Cu wire			
Reason for Change:					
Continuity of supply.					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Anticipated impact on Material Declaration					
<input checked="" type="checkbox"/>	No Impact to the Material Declaration	<input type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI Eco-Info website . There is no impact to the material meeting current regulatory compliance requirements with this PCN change.		
Changes to product identification resulting from this PCN:					
None					
Product Affected:					
LM358LVDR	MCP6292IDR	SN1711004DR	TLV9062IDR		
LMV358AIDR	SN1605025DR	TLV9002IDR	TSV912AIDR		

Qualification Report

TLV9062IDR - New Capillary & Wire Diam

Approve Date 04-Sep-2018

Product Attributes

Attributes	Qual Device: <u>TLV9062ID</u>	QBS Product Reference: <u>TLV9062ID</u>	QBS Process Reference: <u>TLV9002ID</u>
Assembly Site	AMK P1	AP1	AP1
Package Family	SOIC	SOIC	SOIC
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	RFAB	RFAB	RFAB
Wafer Process	LBC9	LBC9	LBC9

- QBS: Qual By Similarity
- Qual Device TLV9062ID is qualified at LEVEL2-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: <u>TLV9062ID</u>	QBS Product Reference: <u>TLV9062ID</u>	QBS Process Reference: <u>TLV9002ID</u>
ED	Electrical Characterization	Per Datasheet Parameters	-	Pass	Pass
ELFR	Early Life Failure Rate, 125C	48 Hours	-	3/2400/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	1/77/0
HBM	ESD - HBM	4000 V	-	3/18/0	-
CDM	ESD - CDM	1500 V	-	3/9/0	1/3/0
HTOL	Life Test, 150C	300 Hours	-	3/231/0	1/77/0
HTSL	High Temp. Storage Bake, 170C	420 Hours	3/231/0	3/231/0	1/77/0
LU	Latch-up	(per JESD78)	-	3/18/0	1/6/0
SD	Solderability	Pb Free	-	3/66/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0	1/77/0
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	3/231/0	3/231/0	1/77/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

THIS INFORMATION RELATING TO QUALITY AND RELIABILITY IS PROVIDED "AS IS." Product information detailed in this report may not accurately reflect TI's current product materials, processes and testing used in the construction of the TI products. Customers are solely responsible to conduct sufficient engineering and additional qualification testing to determine whether a device is suitable for use in their applications. Using TI products outside limits stated in TI's datasheet may void TI's warranty. See TI's Terms of Sale at <http://www.ti.com/lsds/ti/legal/termsofsale.page>

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com